

| L Number | Hits | Search Text  | DB  | Time stamp       |
|----------|------|--|---|------------------|
| 1        | 669  | 156/\$.ccls. and (b adj stage\$3)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 11:42 |
| 2        | 659  | (156/\$.ccls. and (b adj stage\$3)) and (@ad<20011214)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 12:50 |
| 3        | 287  | ((156/\$.ccls. and (b adj stage\$3)) and (@ad<20011214)) and (chip or die or wafer or silicon)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 11:33 |
| 4        | 69   | (b adj stage\$3) near (mixture or combination)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 11:58 |
| 5        | 17   | (cure near (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl)))) and (cure near (epoxy or (epoxy near imidazole)))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 12:44 |
| 6        | 0    | 2001083652.URPN.   | USPAT   | 2003/03/06 12:29 |
| 7        | 194  | (first and second) near cure   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 12:34 |
| 8        | 3    | ((first and second) near cure) and (cure with (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl)))) and (cure with (epoxy or (epoxy near imidazole)))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 13:37 |
| 9        | 2644 | 156/\$.ccls. and (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl))) and (epoxy or (epoxy near imidazole))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 12:46 |
| 10       | 1186 | (156/\$.ccls. and (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl))) and (epoxy or (epoxy near imidazole))) and cure   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 12:47 |
| 11       | 576  | (156/\$.ccls. and (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl))) and (epoxy or (epoxy near imidazole))) and (cure with (heat or temperature))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 12:49 |
| 12       | 569  | ((156/\$.ccls. and (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl))) and (epoxy or (epoxy near imidazole))) and (cure with (heat or temperature))) and (@ad<20011214)                                       | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 13:42 |
| 13       | 246  | ((156/\$.ccls. and (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl))) and (epoxy or (epoxy near imidazole))) and (cure with (heat or temperature))) and (@ad<20011214) and (chip or die or silicon or wafer) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 13:09 |
| 14       | 277  | (dual adj cur\$3) and (chip or die or wafer or silicon)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 13:11 |

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| 15 | 261  | ((dual adj cur\$3) and (chip or die or wafer or silicon)) and (@ad<20011214)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 13:18 |
| 16 | 181  | ((((dual adj cur\$3) and (chip or die or wafer or silicon)) and (@ad<20011214)) and (cur\$3 with (heat or temperature)))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 13:25 |
| 17 | 7    | ((((dual adj cur\$3) and (chip or die or wafer or silicon)) and (@ad<20011214)) and wafer   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 13:29 |
| 18 | 82   | cur\$ near ((filler or globule or pellet or particle)and (liquid or solvent))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 13:32 |
| 19 | 83   | cur\$3 near ((filler or globule or pellet or particle)and (liquid or solvent))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 13:35 |
| 20 | 83   | cur\$3 near ((filler or globule or pellet or particle) and (liquid or solvent))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 13:35 |
| 21 | 7    | (cur\$3 near ((filler or globule or pellet or particle)and (liquid or solvent))) and ((filler or globule or pellet or particle) near (liquid or solvent))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 13:36 |
| 22 | 384  | ((((Liquid or solvent) and cure) with (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl)))) and (epoxy or (epoxy near imidazole)))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 13:41 |
| 23 | 60   | ((((Liquid or solvent) and cure) with (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl)))) and (epoxy or (epoxy near imidazole))) and ((underfill or adhesive) and (chip or die or wafer or silicon))                      | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 13:42 |
| 24 | 57   | (((((Liquid or solvent) and cure) with (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl)))) and (epoxy or (epoxy near imidazole))) and ((underfill or adhesive) and (chip or die or wafer or silicon))) and (@ad<20011214) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 13:54 |
| 25 | 2328 | (liquid near (mixture or combination)) and (dual or (first and second) near cure)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 13:55 |
| 26 | 2246 | ((liquid near (mixture or combination)) and (dual or (first and second) near cure) ) and (@ad<20011214)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 13:55 |
| 27 | 0    | ((((liquid near (mixture or combination)) and (dual or (first and second) near cure) ) and (@ad<20011214)) and ((liquid and solvent) near cure)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 14:07 |

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| 28 | 0  | "L29" and ((liquid and solvent) near cure)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 14:13 |
| 29 | 0  | ((((liquid near (mixture or combination)) and (dual or (first and second) near cure) ) and (@ad<20011214)) and ((liquid and solvent) near cure) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 14:15 |
| 30 | 11 | ((((liquid near (mixture or combination)) and (dual or (first and second) near cure) ) and (@ad<20011214)) and ((liquid and solvent) with cure) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/03/06 14:15 |